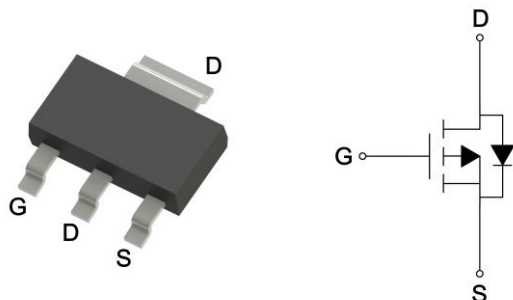


Product Summary

BV_{DSS}	-100	V
$R_{DS(ON)}$ typ. @ $V_{GS}=-10V$, $I_D=-2A$	190	m Ω
I_D @ $V_{GS}=-10V$, $T_C=25^\circ C$	-6	A
I_D @ $V_{GS}=-10V$, $T_A=25^\circ C$	-2	

SOT-223



Ordering Information

Device	Package	Shipping
MTE160P10L3-0-T3-G	SOT-223	2500pcs / Tape & Reel

0: Product rank, zero for no rank products.

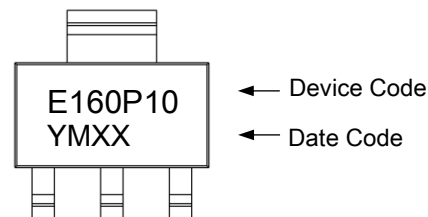
T3: Packing spec, T3 : 2500pcs / tape & reel, 13" reel

G: Environment friendly grade: S for RoHS compliant products, G for RoHS compliant and green compound products.

Features

- Low On Resistance
- Low Gate Charge
- Fast Switching Characteristic
- Pb-free lead plating and halogen-free

Marking



YMXX: Date Code Marking

Y: Year Code, the last digit of Christian year

M: Month Code

A: Jan	B: Feb	C: Mar	D: Apr	E: May	F: Jun
G: Jul	H: Aug	J: Sep	K: Oct	L: Nov	M: Dec

XX: Production Serial Number, 01~99

Absolute Maximum Ratings ($T_A=25^\circ C$)

Parameter		Symbol	Value	Unit
Drain-Source Voltage		V _{DS}	-100	V
Gate-Source Voltage		V _{GS}	±20	
Continuous Drain Current @ V _{GS} =-10V, T _C =25°C		I _D	-6	A
Continuous Drain Current @ V _{GS} =-10V, T _C =100°C			-3.8	
Continuous Drain Current @ V _{GS} =-10V, T _A =25°C			-2	
Continuous Drain Current @ V _{GS} =-10V, T _A =70°C			-1.6	
Pulsed Drain Current		I _{DM}	-24	
Continuous Body Diode Forward Current @ T _C =25°C		I _S	-6	
Pulsed Body Diode Forward Current @ T _C =25°C		I _{SM}	-24	
Avalanche Current @ L=0.1mH		I _{AS}	-15	mJ
Avalanche Energy @ L=0.5mH		E _{AS}	16	
Total Power Dissipation	T _C =25°C	P _D	17	W
	T _C =100°C		6.8	
	T _A =25°C		2.2	
	T _A =70°C		1.4	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55~+150	°C
Steady State Thermal Resistance, Junction-to-Case		R _{θJC}	7.3	°C/W
Steady State Thermal Resistance, Junction-to-Ambient		R _{θJA}	58	

Electrical Characteristics ($T_A=25^{\circ}\text{C}$, unless otherwise specified)

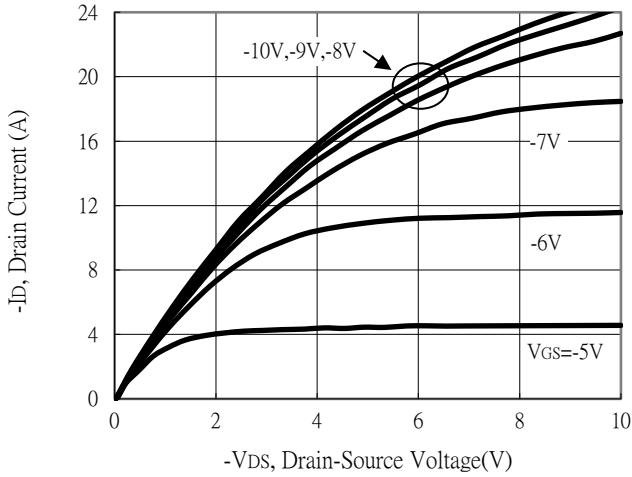
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static					
BV _{DSS}	-100	-	-	V	V _{GS} =0V, I _D =-250μA
V _{GS(th)}	-2	-	-4		V _{DS} =V _{GS} , I _D =-250μA
G _{FS}	-	3.6	-	S	V _{DS} =-10V, I _D =-2A
I _{GSS}	-	-	±100	nA	V _{GS} =±20V, V _{DS} =0V
I _{DSS}	-	-	-1	μA	V _{DS} =-80V, V _{GS} =0V
R _{DS(ON)}	-	190	247	mΩ	V _{GS} =-10V, I _D =-2A
Dynamic					
C _{iss}	-	520	-	pF	V _{DS} =-50V, V _{GS} =0V, f=1MHz
C _{oss}	-	55	-		
C _{rss}	-	27	-		
R _g	-	11	-	Ω	f=1MHz
Q _g *d,e	-	9.7	-	nC	V _{DS} =-50V, I _D =-2A, V _{GS} =-10V
Q _{gs} *d,e	-	2.7	-		
Q _{gd} *d,e	-	2.2	-		
t _{d(ON)} *d,e	-	8.6	-	ns	V _{DS} =-50V, I _D =-2A, V _{GS} =-10V, R _{GS} =1Ω
t _r *d,e	-	18	-		
t _{d(OFF)} *d,e	-	25	-		
t _f *d,e	-	24	-		
Source-Drain Diode					
V _{SD} *d	-	-0.8	-1.2	V	I _S =-2A, V _{GS} =0V
t _{rr}	-	24	-	ns	I _F =-2A, di/dt=100A/μs
Q _{rr}	-	25	-	nC	

Note:

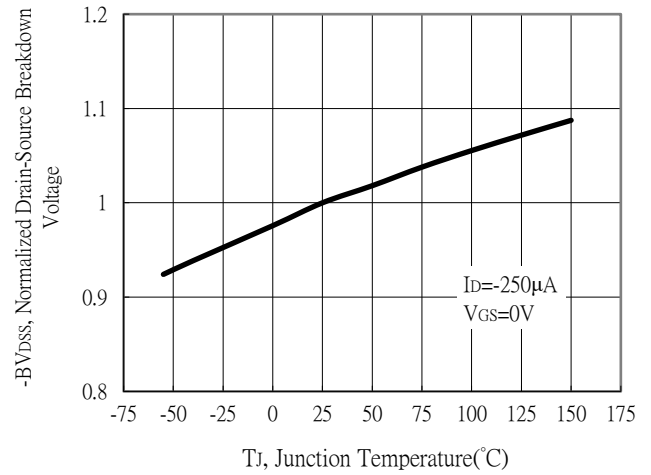
- *a. The power dissipation P_D is based on $T_{J(MAX)}=150^{\circ}\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper Dissipation.
- *b. The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz copper, in a still air environment with $T_A=25^{\circ}\text{C}$. The power dissipation P_D is based on $R_{\theta JA}$ and the maximum allowed junction temperature of 150°C . The value in any given application depends on the user's specific board design.
- *c. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}=150^{\circ}\text{C}$. Ratings are based on low frequency and low duty cycles to keep initial $T_J=25^{\circ}\text{C}$.
- *d. Pulse Test : Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
- *e. Independent of operating temperature.

Typical Characteristics

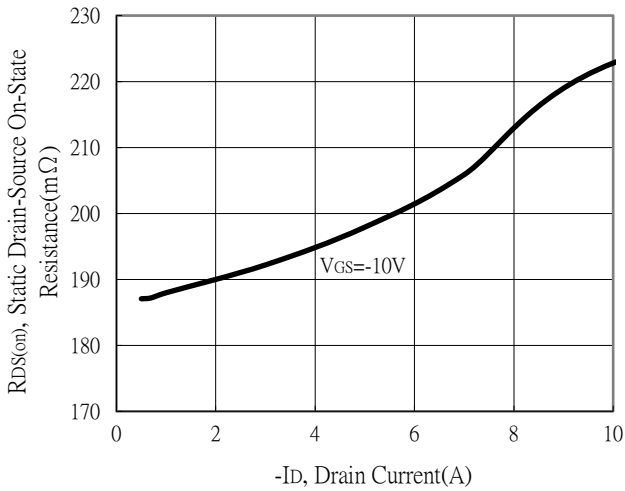
Typical Output Characteristics



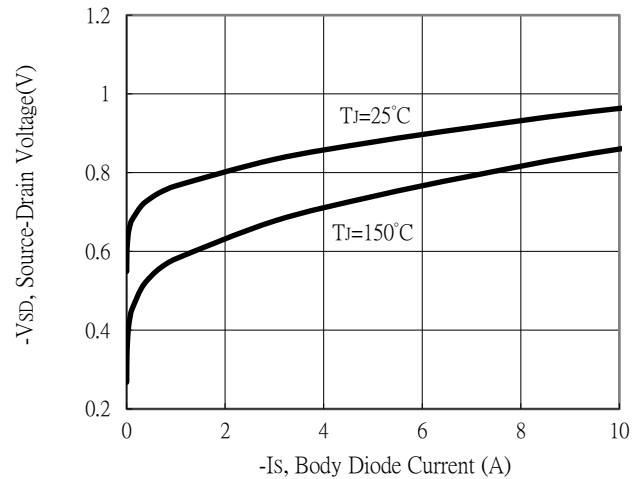
Breakdown Voltage vs Ambient Temperature



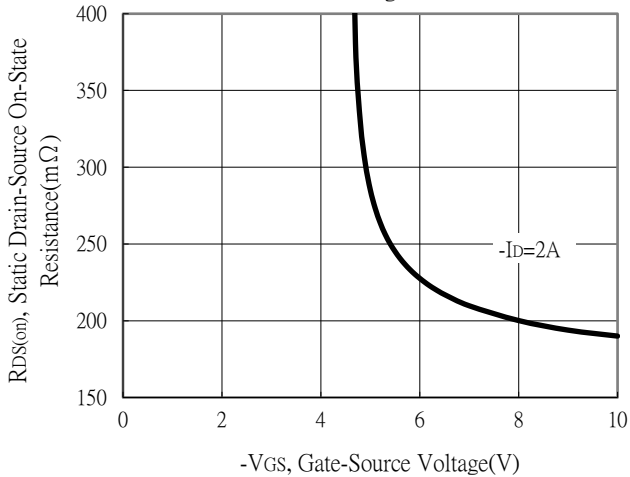
Static Drain-Source On-State resistance vs Drain Current



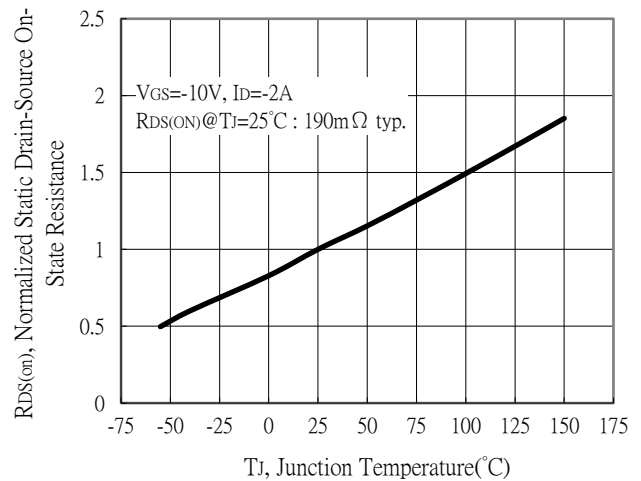
Body Diode Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage

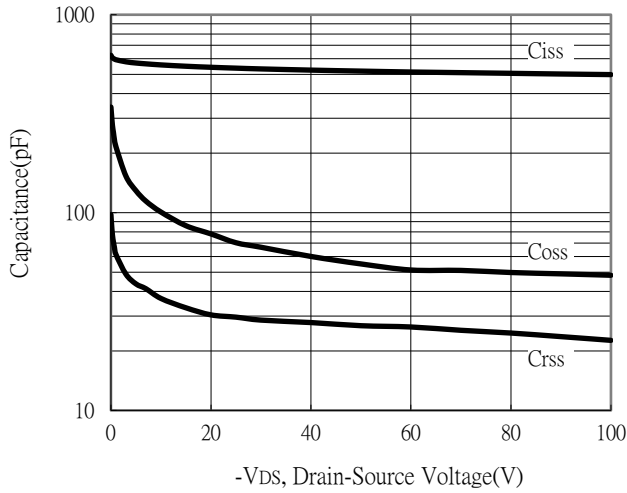


Drain-Source On-State Resistance vs Junction Temperature

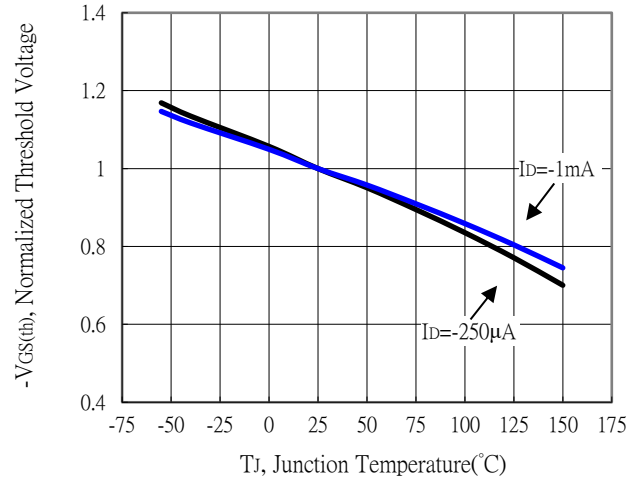


Typical Characteristics

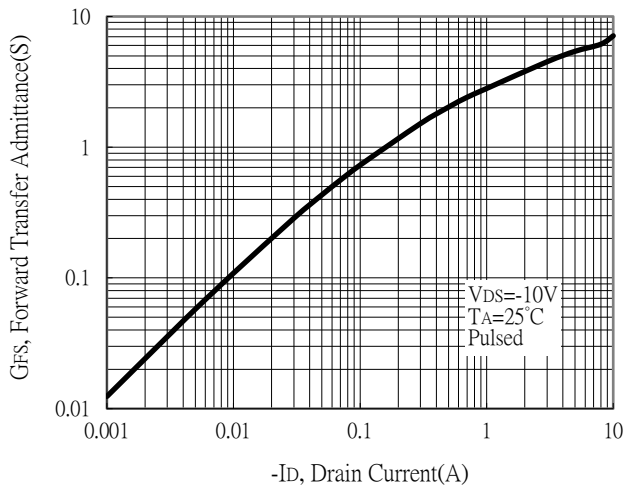
Capacitance vs Drain-to-Source Voltage



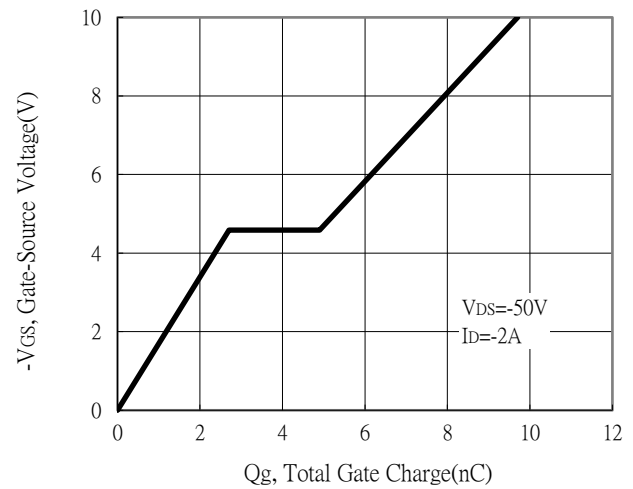
Threshold Voltage vs Junction Temperature



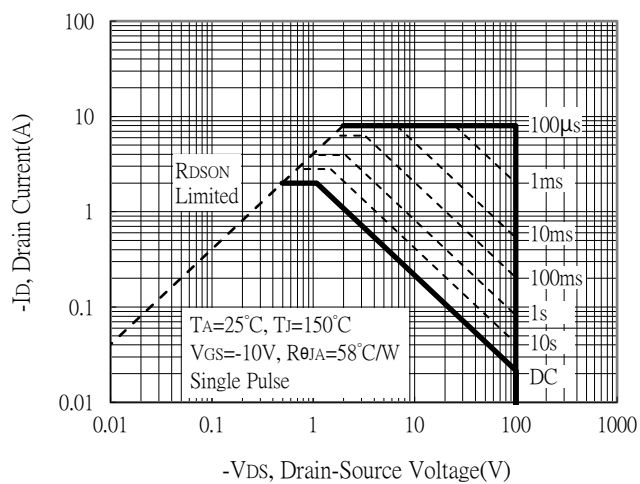
Forward Transfer Admittance vs Drain Current



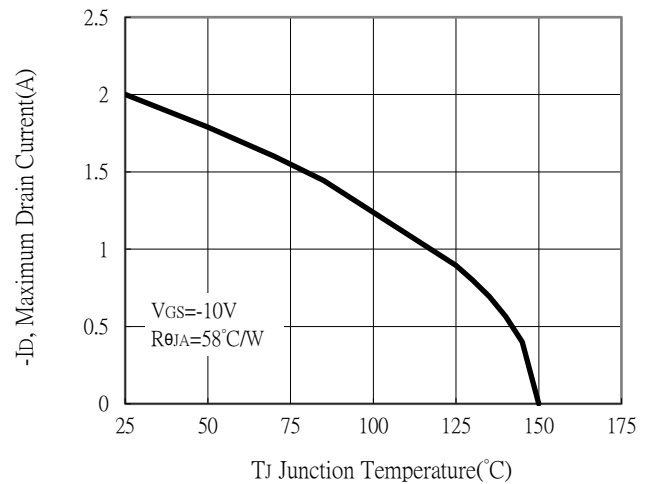
Gate Charge Characteristics



Maximum Safe Operating Area

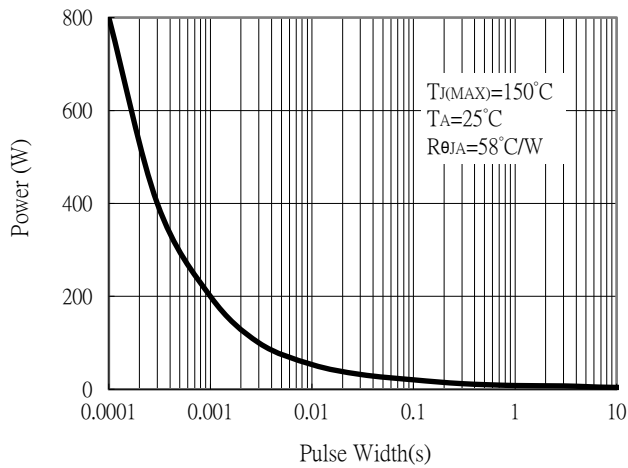


Maximum Drain Current vs Junction Temperature

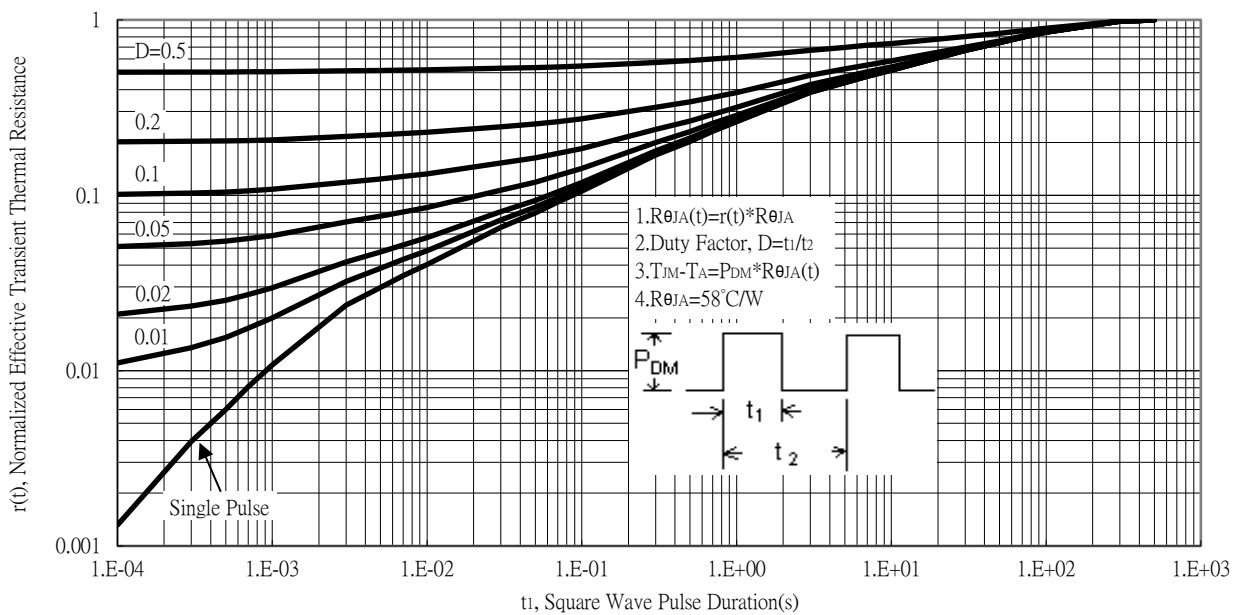


Typical Characteristics

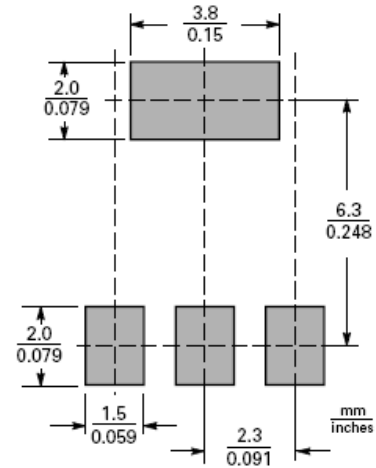
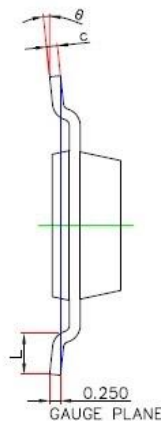
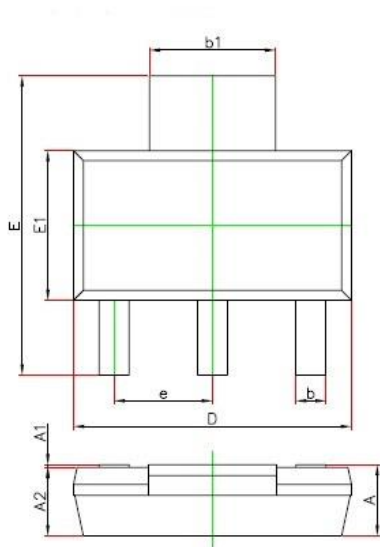
Single Pulse Power Rating, Junction to Ambient



Transient Thermal Response Curves



SOT-223 Dimension


Unit ($\frac{\text{mm}}{\text{inch}}$)

3-Lead SOT-223 Plastic Surface Mount Package
CYStek Package Code: L3

Recommended Soldering Footprint

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	-	0.071	-	1.800	D	0.248	0.264	6.300	6.700
A1	0.001	0.004	0.020	0.100	E	0.264	0.287	6.700	7.300
A2	0.059	0.067	1.500	1.700	E1	0.130	0.146	3.300	3.700
b	0.026	0.033	0.660	0.840	e	0.091	BSC	2.300	BSC
b1	0.114	0.122	2.900	3.100	L	0.030	-	0.750	-
c	0.009	0.014	0.230	0.350	θ	0°	10°	0°	10°

Note:

- Controlling dimension: millimeters.
- Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
- If there is any question with packing specification or packing method, please contact your local CYStek sales office.

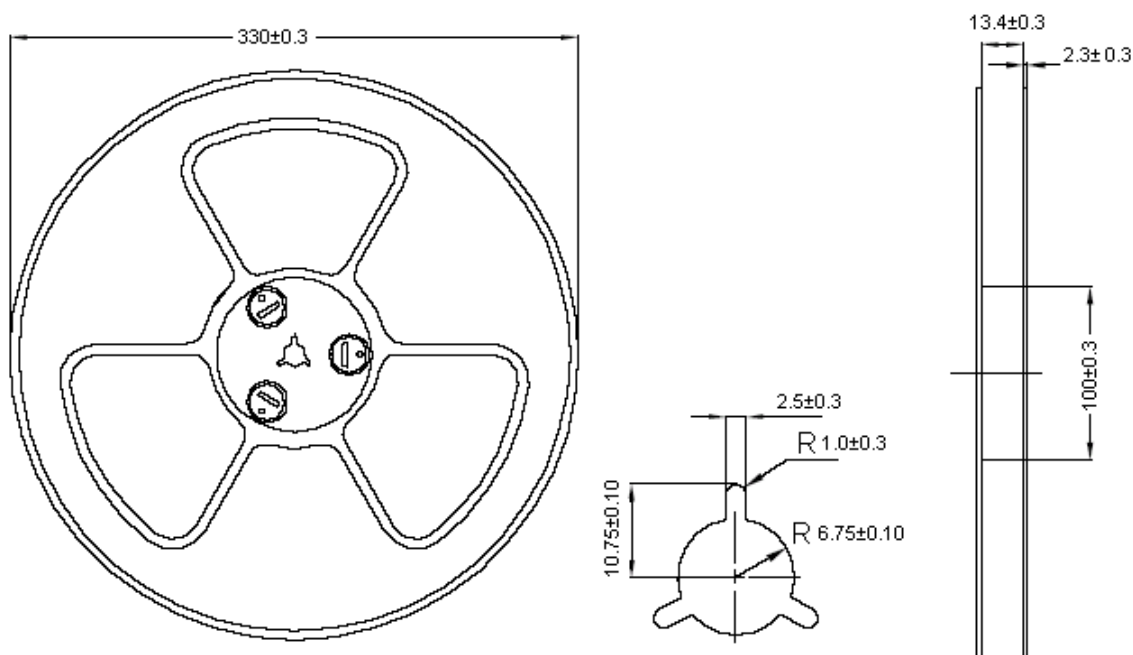
Material:

- Lead: pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0.

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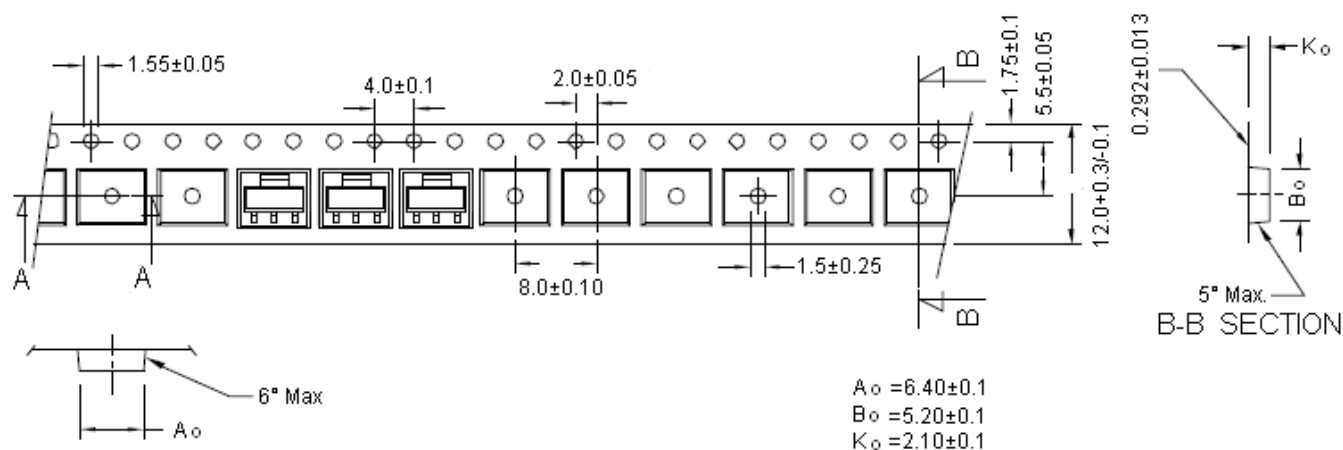
Reel Dimension



UNIT : mm

NOTE : 1. Material : Anti-static polystyrene
2. Surface resistivity $10^9 \Omega/\text{sq}$

Carrier Tape Dimension


$$\begin{aligned} A_o &= 6.40 \pm 0.1 \\ B_o &= 5.20 \pm 0.1 \\ K_o &= 2.10 \pm 0.1 \end{aligned}$$

A-A SECTION

Notes:

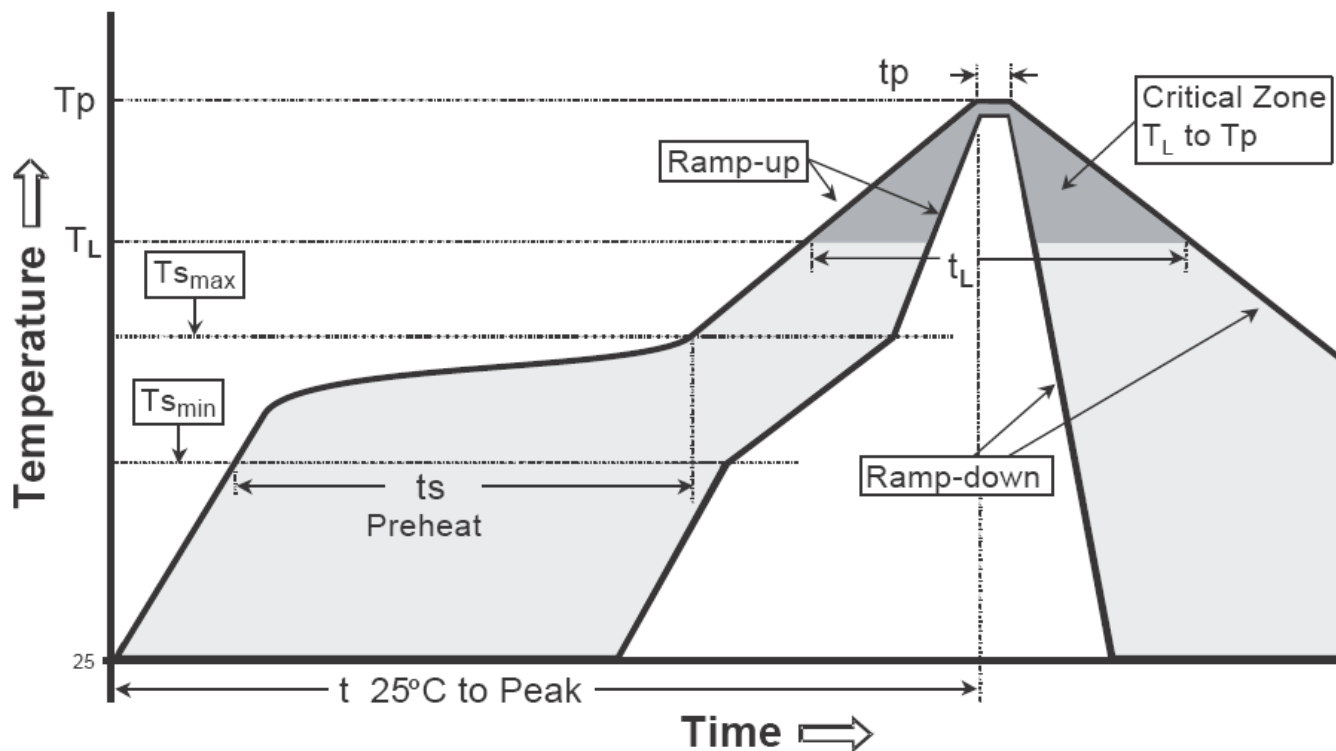
1. 10 sprocket hole pitch cumulative tolerance ± 0.2 .
2. Camber not to exceed 1mm in 100mm.
3. Material: conductive black polystyrene
4. Ao & Bo measured on a plane 0.3mm above the bottom of the pocket.
5. Ko measured from a plane on the inside bottom of the pocket to the top surface of the carrier.
6. Pocket position relative to sprocket hole measured as true position of pocket, not pocket hole.

Uni : millimeter

Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (Ts max to TP)	3°C/second max.	3°C/second max.
Preheat -Temperature Min (Ts min) -Temperature Max (Ts max) -Time (ts min to ts max)	100°C 150°C 60-120 seconds	150°C 200°C 60-180 seconds
Time maintained above: -Temperature (TL) -Time (tL)	183°C 60-150 seconds	217°C 60-150 seconds
Peak Temperature (TP)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature (tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note:

- All temperatures refer to topside of the package, measured on the package body surface.